Specification of Thermoelectric Module

TEC1-19912

Description

The 199 couples, 40 mm \times 40 mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

Performance Specification Sheet

Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Th(°C)	27	50	Hot side temperature at environment: dry air, N ₂	
DT _{max} (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U _{max} (Voltage)	25.0	26.6	Voltage applied to the module at DT _{max}	
I _{max(} amps)	11.3	11.3	DC current through the modules at DT _{max}	
Q _{Cmax} (Watts)	177.3	191.7	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance(ohms)	1.70	1.88	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters

40.0 ± 0.3 Ŧ Positive lead wire (Red) 40.0 ± 0.3 18AWG leads, PVC insulated Negative lead wire (Black) 150 ± 3 Cold side: To See ordering option Hot side: Th 7 See ordering option //See ordering option A

Thickness

1:3.2±0.03

(mm)0:3.2±0.1

Suffix

TF

TF

Ordering Option

Standard/

Flatness/

Parallelism (mm)

0:0.05/0.08

1:0.03/0.03

Eg. TF01: Thickness 3.2 ± 0.1 (mm) and Flatness 0.03/0.03 (mm)

Manufacturing Options

E	A. Solder:	B. Sealant:	
	1. T100: BiSn (Tmelt=138°C)	1. NS: No sealing (Standard)	
	2. T200: CuAgSn (Tmelt = 217°C)	2. SS: Silicone sealant	
	3. T240: SbSn (Tmelt = 240°C)	3. EPS: Epoxy sealant	
	C. Ceramics:	D. Ceramics Surface Options:	
	1. Alumina (Al ₂ O ₃ , white 96%)	1. Blank ceramics (not metalized)	
	2. Aluminum Nitride (AlN)	2. Metalized	
n	Namin	g for the Module	
Lead wire ler	ngth(mm) TEC1-19912- X-X	ТЕС1-19912- х-х-х-х тттт	
Standard/Optio	onal length	Ceramics Flatness/ Parallelism	
150±3/Sp	becify	Sealant	

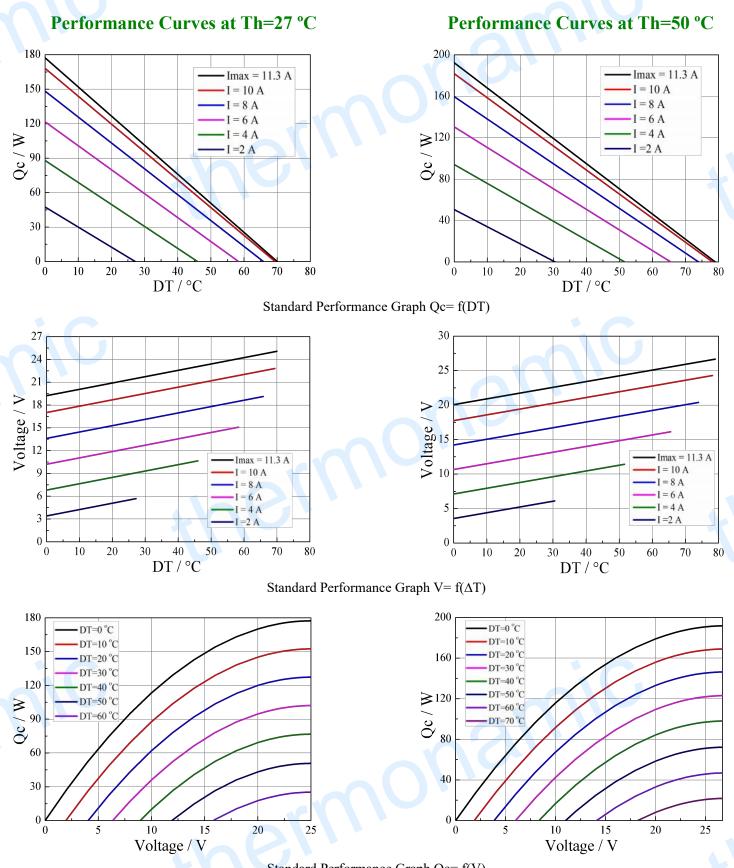
Solder TEC1-19912-T200 -NS -TF01 -AlO T200: CuSn (Tmelt=227°C) NS: No sealing AlO: Alumina white 96%

TF01: Thickness ±0.1(mm) and Flatness/Parallelism (mm): 0.025/0.025

150±3/Specify

Specification of Thermoelectric Module

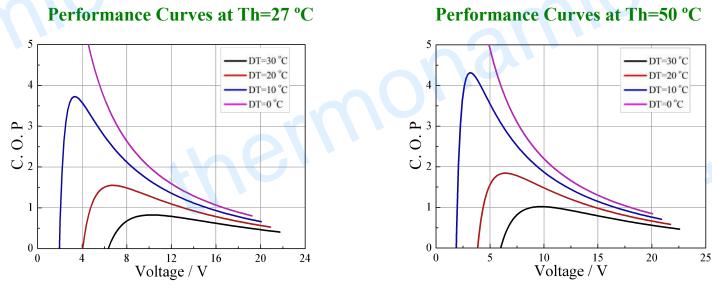
TEC1-19912



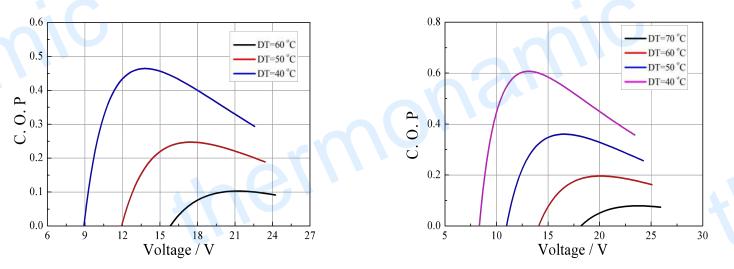
Standard Performance Graph Qc = f(V)

Specification of Thermoelectric Module

TEC1-19912



Standard Performance Graph COP = f(V) of ΔT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of ΔT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating.
- Storage module below 100 °C
- \bullet Operation below I_{max} or V_{max}
- Work under DC